

TFW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
BEFORE THE COMMISSIONER OF PATENTS

Appl. No. : 10/812,890
Applicant : R. Japp, et al
Filed : 3/31/04
TC/A.U. : 2811
Examiner :
Docket No. : EI-2-04-003
Title: : **Circuitized Substrate, Method of Making Same, Electrical
Assembly Utilizing Same and Information Handling System
Utilizing Same**
Assignee : Endicott Interconnect Technologies, Inc.

Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

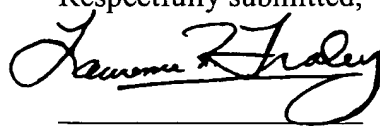
STATUS INQUIRY

Applicants request the status of the above application. The application was filed on 03/31/04. A copy of the return postcard is attached for the Examiner's convenience. A Filing Receipt was received 06/09/04. A copy is attached for the Examiner's convenience. A Change of Correspondence Address was filed 07/20/04. A copy of this return postcard is also attached for the Examiner's convenience.

Because Applicants have heard nothing further as of this date, a status is requested. Please advise when we may expect a communication with respect to the above-referenced application. A stamped, self-addressed envelope is enclosed herewith for your use in responding to this request.

An e-mail response to the undersigned at the email address below or a phone response is encouraged to expedite a response to this inquiry.

Telephone: (561) 575-3608
Fax : (561) 745-2741

Respectfully submitted,


Lawrence R. Fraley
Reg. No: 26,885
Attorney for Applicants
Date: April 28, 2005
e-mail: Lawrence.Fraley@eitny.com



RECEIVED

APR 08 2004

Date: 3/30/04
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Please Acknowledge and Return

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|---|--|
| <input checked="" type="checkbox"/> Application | <input type="checkbox"/> Issue Fee |
| <input checked="" type="checkbox"/> Declaration <u>3</u> pgs. | <input type="checkbox"/> Draftsman w/Dwgs. |
| <u>x</u> signed <u> </u> unsigned | <input checked="" type="checkbox"/> Cert. of Mailing |
| <input checked="" type="checkbox"/> Assignment w/Cover Pg. | <input type="checkbox"/> |
| <input checked="" type="checkbox"/> IDS/PTO-1449/Refs. | |
| <input type="checkbox"/> Amendment | |

Title Circuitized Substrate, Method of Making Same,
Electrical Assembly Utilizing Same, And Information
Handling System Utilizing Same

27 Pgs. Spec. 34 Claims 2 Shts. of Drawing
Filing Fee Attorney Lawrence Fraley
Docket EI-2-04-003
In Appln. Of R. Japp et al
Serial/Inter. Number
Filed Herewith

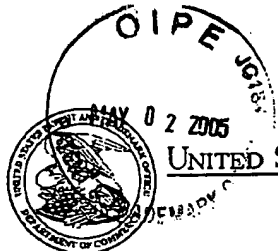
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22553 U.S. PTO
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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/812,890	03/31/2004	2811	1194	EI-2-04-003	2	34	5

CONFIRMATION NO. 5018

Lawrence R. Fraley, IP Law Counsel
 Endicott Interconnect Technologies, Inc.
 1701 North Street, 0099/257-4 AA12
 Endicott, NY 13760

FILING RECEIPT



OC000000012907862

Date Mailed: 06/09/2004

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Robert Japp, Vestal, NY;
 Voya Markovich, Endwell, NY;
 Cheryl Palomaki, Endicott, NY;
 Kostas Papathomas, Endicott, NY;
 David L. Thomas, Endicott, NY;

Assignment For Published Patent Application

Endicott Interconnect Technologies, Inc., Endicott, NY;

Domestic Priority data as claimed by applicant

Foreign Applications

If Required, Foreign Filing License Granted: 06/08/2004

Projected Publication Date: 10/06/2005

Non-Publication Request: No

Early Publication Request: No

Title

Date: 7/15/04
Express Mail No.: _____

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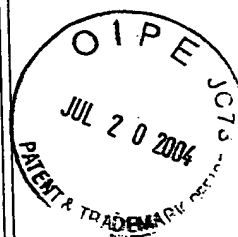
- ☐ Application
☐ Declaration ____ pgs.
____ signed ____ unsigned
☐ Assignment w/Cover Pg.
☐ IDS/PTO-1449/Refs.
☐ Amendment

- ☐ Issue Fee
☐ Draftsman w/Dwgs.
☒ Cert. of Mailing
Change of
correspondence
Address

Title Circuitized Substrate Method of Making
Same, Electrical Assembly Utilizing Same and
Information Handling System Utilizing Same

____ Pgs. Spec. 1 Claims ____ Shts. of Drawing
____ Filing Fee Attorney Lawrence Fraley
____ Docket EE-2-04-003
In Appln. Of R. Japp et al
Serial/Inter. Number 10/812, P90
Filed 3/31/04

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Certificate of Mailing under 37 CFR 1.8

I hereby certify that this correspondence is being deposited with United States Postal Service in an envelope addressed to:

**Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450**

On April 28, 2005.

Signature

Christine Lang

Typed or printed name of person of signing Certificate

EI-2-04-003 – Status Inquiry, Post Card, Copy of Application Return Post Card, Copy of Filing Receipt, Copy of Change of Correspondence Address Post Card, Stamped, Self-Addressed Envelope.

Note: Each paper must have its own certificate of mailing, or this certificate must identify each submitted paper.